IPC  ASSOCIATION CONNICELECTRONICS INDUS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
upplier Info	formation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2025-05-11			
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-St	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Rep	presentative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
Product-Env-St	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requ	Requester Item Number		Number	Mfr Item Name			Effective Date	Version Manufacturing Site		Ianufacturing Site	We	ight*	UOM	Unit Type
		NCV70514MW007R2 C514B-Cold Book		C514B-Cold Boost			2025-05-11 PHG		HG	14.8	3	mg	Each	
Ianufacturi	ing Proccess Informa	ation												
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL	D-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature					Temperature	Numb	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed		C	CU Alloy 1				260	<b>260</b> C		30 seco		3		
omments														
vel 1 - maximu	um time at peak temperat	ure during sol	dering is 10-3	0 seconds										
or more inform	mation regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Iomogeneous Material Weight		Unit of Measure	Level Substance		CAS	Exempt	Weight	Unit of Measure
Die	0.25	mg	Supplier	Silicon (Si)	7440-21-3		0.25	mg
Die Attach Epoxy	0.37	mg		Epoxy resin	proprietary data		0.2405	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.1295	mg
Lead Frame	5.81		Supplier	Silver (Ag)	7440-22-4		0.9877	mg
			Supplier	Iron (Fe)	7439-89-6		0.0465	mg
			Supplier	Copper (Cu)	7440-50-8		4.7758	mg
Mold Compound-Black	7.0	mg		Epoxy Phenol Resin	proprietary data		0.735	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.265	mg
Plating	0.41	mg	Supplier	Tin (Sn)	7440-31-5		0.41	mg
Wire Bond - Au	0.96	mg	Supplier	Gold (Au)	7440-57-5		0.96	mg